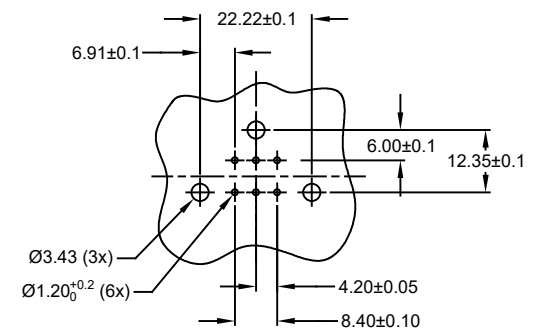
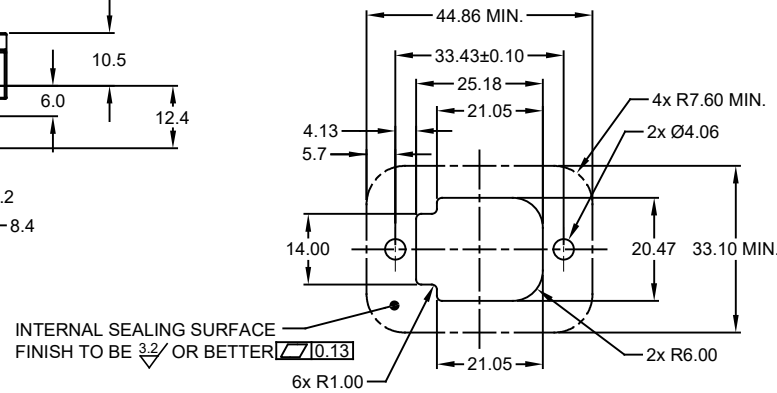
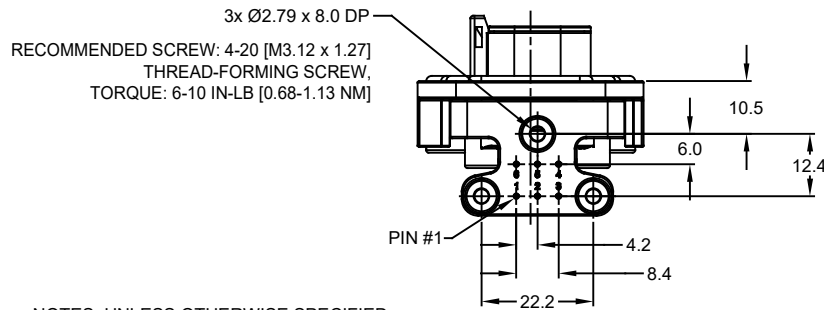
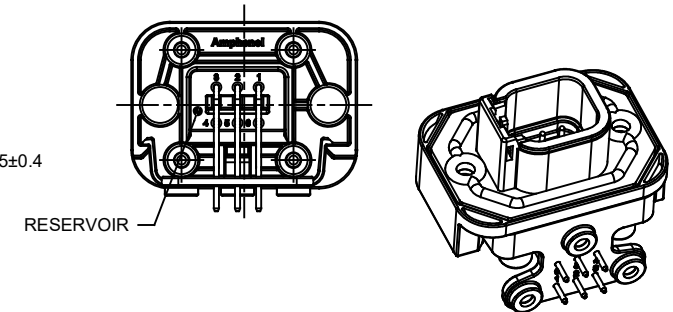
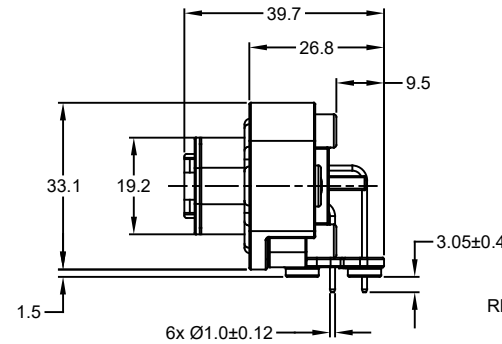
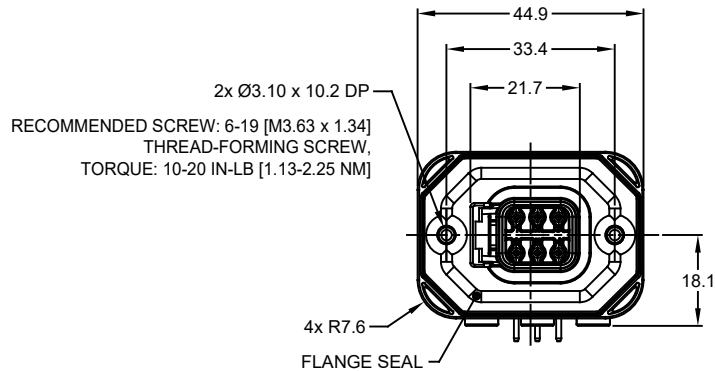


REVISIONS					
REV	ECO	DESCRIPTION	DATE	BY	APPR
A1	-	RELEASE NEW DRAWING	15JUN18	SULLEN	TOMMY
A2	-	REVISED DRAWING	10JUL20	JHEAD	DH



RECOMMENDED PCB LAYOUT
VIEW FROM COMPONENTS
SIDE OF PCB

NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL:
HOUSING: THERMOPLASTIC, GREY
SEAL: SILICONE RUBBER
CONTACT: COPPER ALLOY
- MODIFICATIONS: FLANGE; RA PCB MOUNT
- SPECIFICATIONS:
3.1 CURRENT RATING: 7.5 AMPS
3.2 OPERATING TEMPERATURE: -55°C TO +125°C
3.3 DIELECTRIC WITHSTANDING VOLTAGE: LESS THAN 2 MILLIAMPS CURRENT LEAKAGE @ 1500 VOLTS AC
3.4 INSULATION RESISTANCE: 1000 MEGOHMS MIN @ 25°C
3.5 MOISTURE RESISTANCE: IP67 (MATED CONDITION)
3.6 MATING CYCLE DURABILITY: 100 CYCLES
3.7 RoHS COMPLIANT

4. MATING PART: ATM06-6S* (* = ALL MODIFICATIONS)

5. ALL DIMENSIONS ARE FOR REFERENCE USE ONLY

6. POTTED CONNECTORS SPECIFIED FOR UP TO 5 P.S.I. APPLICATIONS.

ATM13-6P-BMXX VARIANTS		
CONTACT PLATING	POTTING OR NOT IN RESERVOIR	PART NUMBER
GOLD	NO POTTING	ATM13-6P-BM01
GOLD	POTTING	ATM13-6P-BM02
TIN	NO POTTING	ATM13-6P-BM03
TIN	POTTING	ATM13-6P-BM04

ATM13-6P-BMXX		PART NUMBER		DESCRIPTION	ITEM
QUANTITY		MATERIALS LIST			
UNLESS OTHERWISE SPECIFIED 1) All dimensions are in metric(mm). 2) Tolerances are as follows: 1 PL DEC ±0.30 Fractions ±1/64 2 PL DEC ±0.15 Angles ±1° 3 PL DEC ±0.08 3) Note reference =		SIGNATURES		DATE	
		DRAWN: SULLEN,ZHANG		15JUN18	
		CHECKED: ORION,LI		15JUN18	
		ENGINEER:			
MATERIAL SPECIFICATIONS:		APPROVAL: TOMMY,XIE		15JUN18	
PROCESS SPECIFICATIONS:		CUSTOMER:			
NEXT ASSY:		THIS DRAWING IS SUPPLIED FOR INFORMATION ONLY. DESIGN FEATURES, SPECIFICATIONS AND PERFORMANCE DATA SHOWN HEREON ARE THE PROPERTY OF THE AMPHENOL CORPORATION. NO RIGHTS OF REPRODUCTION ARE IMPLIED. ALL DIMENSIONS ARE SUBJECT TO NORMAL MANUFACTURING VARIATIONS.			
		SIZE: B C-		TYPE: Dwg NO: ATM13-6P-BMXX	
		SCALE: NONE		REVISION: A2	
				SHEET 1 OF 1	